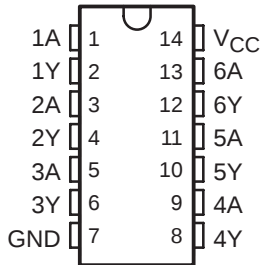


SN54LVU04A, SN74LVU04A HEX INVERTERS

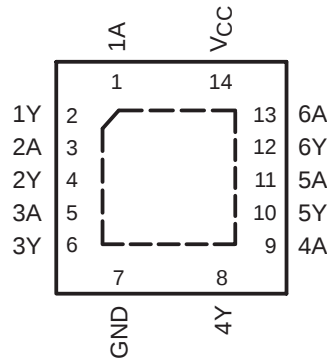
SCES130L – MARCH 1998 – REVISED DECEMBER 2004

- 2-V to 5.5-V V_{CC} Operation
- Unbuffered Outputs
- Max t_{pd} of 6.5 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
<0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot)
>2.3 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Support Mixed-Mode Voltage Operation on All Ports
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

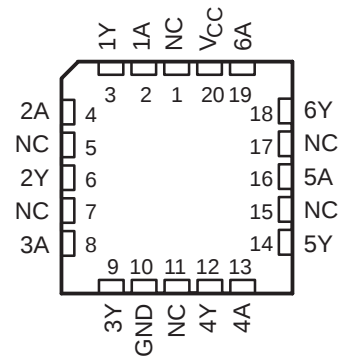
SN54LVU04A . . . J OR W PACKAGE
SN74LVU04A . . . D, DB, DGV, NS,
OR PW PACKAGE
(TOP VIEW)



SN74LVU04A . . . RGY PACKAGE
(TOP VIEW)



SN54LVU04A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

These hex inverters are designed for 2-V to 5.5-V V_{CC} operation.

The 'LVU04A devices contain six independent inverters with unbuffered outputs. These devices perform the Boolean function $Y = \bar{A}$.

ORDERING INFORMATION

T_A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Reel of 1000	SN74LVU04ARGYR	LVU04A
	SOIC – D	Tube of 50	SN74LVU04AD	LVU04A
		Reel of 2500	SN74LVU04ADR	
	SOP – NS	Reel of 2000	SN74LVU04ANSR	LVU04A
	SSOP – DB	Reel of 2000	SN74LVU04ADBR	LU04A
	TSSOP – PW	Tube of 90	SN74LVU04APW	LU04A
		Reel of 2000	SN74LVU04APWR	
		Reel of 250	SN74LVU04APWT	
	TVSOP – DGV	Reel of 2000	SN74LVU04ADGVR	LU04A
–55°C to 125°C	CDIP – J	Tube of 25	SNJ54LVU04AJ	SNJ54LVU04AJ
	CFP – W	Tube of 150	SNJ54LVU04AW	SNJ54LVU04AW
	LCCC – FK	Tube of 85	SNJ54LVU04AFK	SNJ54LVU04AFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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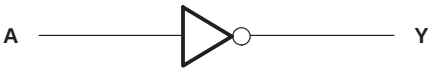
SN54LVU04A, SN74LVU04A
HEX INVERTERS

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FUNCTION TABLE
(each inverter)

INPUT A	OUTPUT Y
H	L
L	H

logic diagram, each inverter (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Output voltage range, V_O (see Notes 1 and 2)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	–20 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V_{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 3): D package	86°C/W
(see Note 3): DB package	96°C/W
(see Note 3): DGV package	127°C/W
(see Note 3): NS package	76°C/W
(see Note 3): PW package	113°C/W
(see Note 4): RGY package	47°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 2. This value is limited to 5.5 V maximum.
 3. The package thermal impedance is calculated in accordance with JESD 51-7.
 4. The package thermal impedance is calculated in accordance with JESD 51-5.

SN54LVU04A, SN74LVU04A HEX INVERTERS

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recommended operating conditions (see Note 5)

		SN54LVU04A		SN74LVU04A		UNIT
		MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	2	5.5	2	5.5	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.7	1.7		V
		V _{CC} = 2.3 V to 2.7 V	V _{CC} × 0.8	V _{CC} × 0.8		
		V _{CC} = 3 V to 3.6 V	V _{CC} × 0.8	V _{CC} × 0.8		
		V _{CC} = 4.5 V to 5.5 V	V _{CC} × 0.8	V _{CC} × 0.8		
V _{IL}	Low-level input voltage	V _{CC} = 2 V	0.3	0.3		V
		V _{CC} = 2.3 V to 2.7 V	V _{CC} × 0.2	V _{CC} × 0.2		
		V _{CC} = 3 V to 3.6 V	V _{CC} × 0.2	V _{CC} × 0.2		
		V _{CC} = 4.5 V to 5.5 V	V _{CC} × 0.2	V _{CC} × 0.2		
V _I	Input voltage	0	5.5	0	5.5	V
V _O	Output voltage	0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 2 V	–50	–50		μA
		V _{CC} = 2.3 V to 2.7 V	–2	–2		mA
		V _{CC} = 3 V to 3.6 V	–6	–6		
		V _{CC} = 4.5 V to 5.5 V	–12	–12		
I _{OL}	Low-level output current	V _{CC} = 2 V	50	50		μA
		V _{CC} = 2.3 V to 2.7 V	2	2		mA
		V _{CC} = 3 V to 3.6 V	6	6		
		V _{CC} = 4.5 V to 5.5 V	12	12		
T _A	Operating free-air temperature	–55	125	–40	85	°C

NOTE 5: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	SN54LVU04A			SN74LVU04A			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V _{OH}	I _{OH} = –50 μA	2 V to 5.5 V	V _{CC} –0.1			V _{CC} –0.1			V
	I _{OH} = –2 mA	2.3 V	2			2			
	I _{OH} = –6 mA	3 V	2.48			2.48			
	I _{OH} = –12 mA	4.5 V	3.8			3.8			
V _{OL}	I _{OL} = 50 μA	2 V to 5.5 V			0.1			0.1	V
	I _{OL} = 2 mA	2.3 V			0.4			0.4	
	I _{OL} = 6 mA	3 V			0.44			0.44	
	I _{OL} = 12 mA	4.5 V			0.55			0.55	
I _I	V _I = 5.5 V or GND	0 V to 5.5 V			±1			±1	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			20			20	μA
C _i	V _I = V _{CC} or GND	3.3 V		4			4		pF

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



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SN54LVU04A, SN74LVU04A HEX INVERTERS

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switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54LVU04A		SN74LVU04A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A	Y	$C_L = 15\text{ pF}$	3.2*	10.9*		1*	14*	1	14	ns
			$C_L = 50\text{ pF}$	6.6	13.4		1	16	1	16	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54LVU04A		SN74LVU04A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A	Y	$C_L = 15\text{ pF}$	2.5*	8.9*		1*	10.5*	1	10.5	ns
			$C_L = 50\text{ pF}$	4.7	11.4		1	13	1	13	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54LVU04A		SN74LVU04A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A	Y	$C_L = 15\text{ pF}$	2.2*	5.5*		1*	6.5*	1	6.5	ns
			$C_L = 50\text{ pF}$	3.9	7		1	8	1	8	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, $V_{CC} = 3.3\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$ (see Note 6)

PARAMETER		SN74LVU04A			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.5	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		-0.1	-0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		3		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage		0.99		V

NOTE 6: Characteristics are for surface-mount packages only.

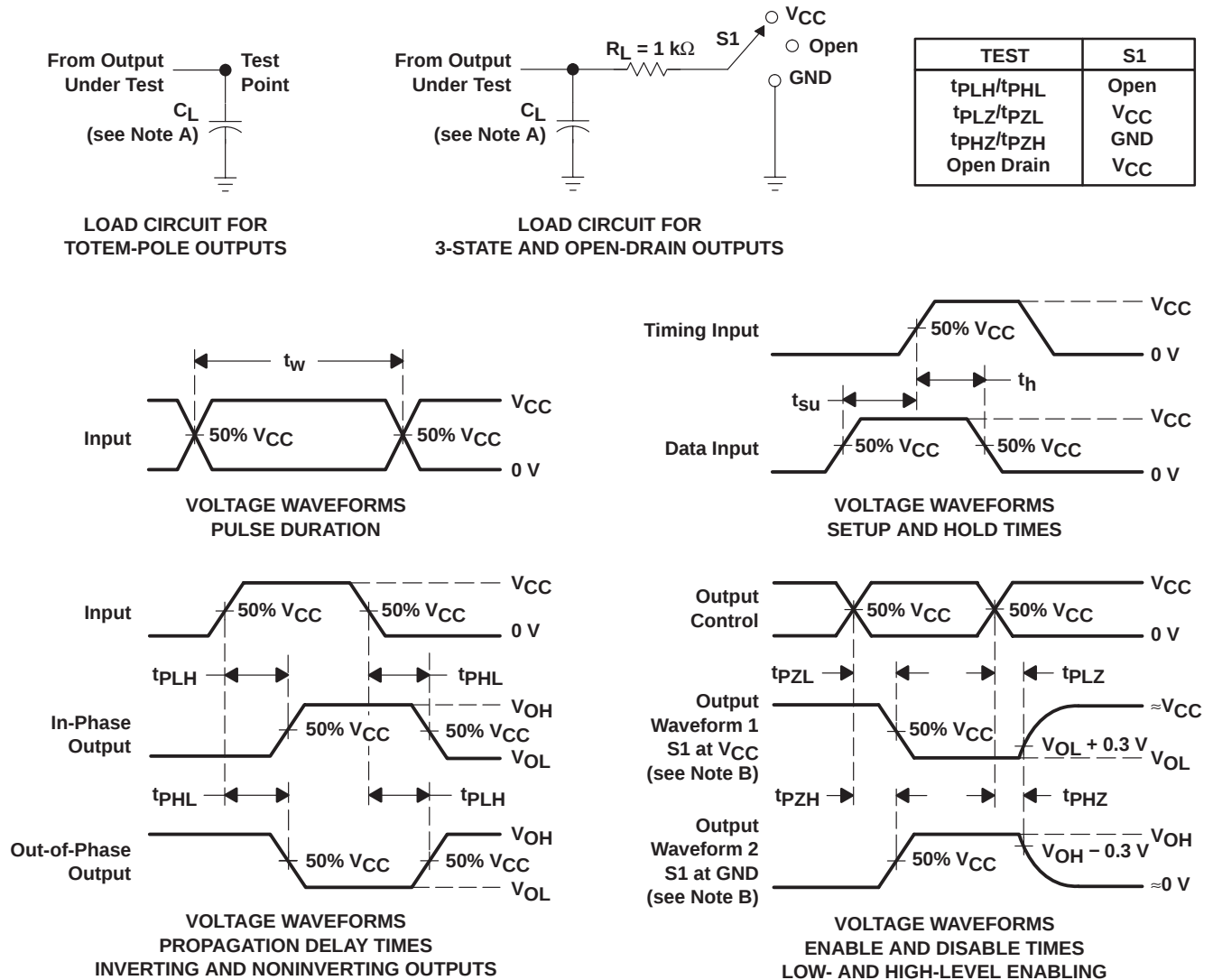
operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	$C_L = 50\text{ pF}$, $f = 10\text{ MHz}$		3.3 V	5.6	pF
				5 V	6.7	

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



PARAMETER MEASUREMENT INFORMATION



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 - The outputs are measured one at a time, with one input transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PHL} and t_{PLH} are the same as t_{pd} .
 - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVU04AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04ADBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI
SN74LVU04ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04ADGVR	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04ADGVRE4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04ADGVRG4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04APW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04APWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04APWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04APWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
SN74LVU04APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04APWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04APWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04APWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04APWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVU04APWTG4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
no Sb/Br)								
SN74LVU04ARGYR	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN74LVU04ARGYRG4	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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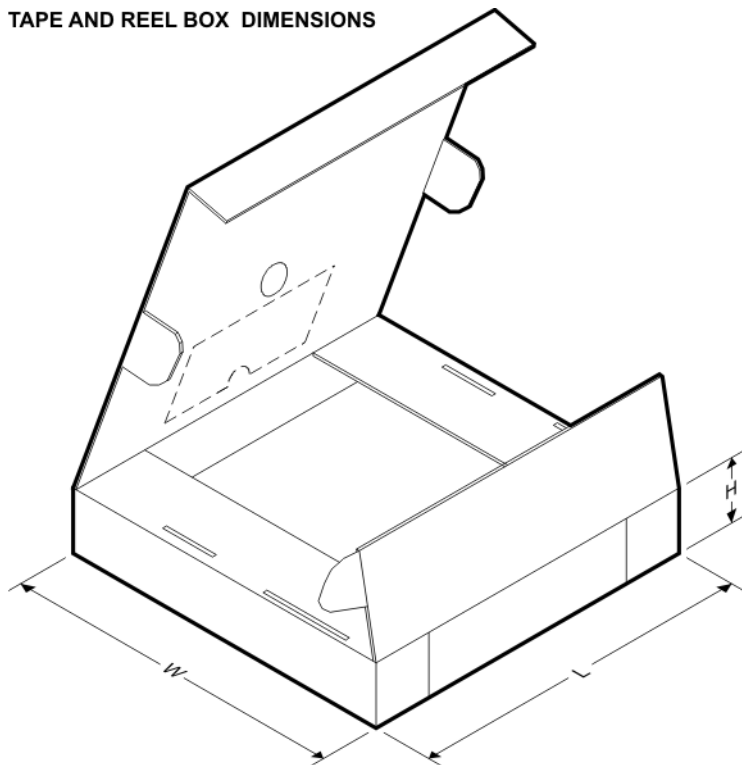
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVU04ADBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LVU04ADGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LVU04ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LVU04ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LVU04APWR	TSSOP	PW	14	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
SN74LVU04ARGYR	QFN	RGY	14	1000	180.0	12.4	3.85	3.85	1.35	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVU04ADBR	SSOP	DB	14	2000	346.0	346.0	33.0
SN74LVU04ADGVR	TVSOP	DGV	14	2000	346.0	346.0	29.0
SN74LVU04ADR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LVU04ANSR	SO	NS	14	2000	346.0	346.0	33.0
SN74LVU04APWR	TSSOP	PW	14	2000	346.0	346.0	29.0
SN74LVU04ARGYR	QFN	RGY	14	1000	190.5	212.7	31.8

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

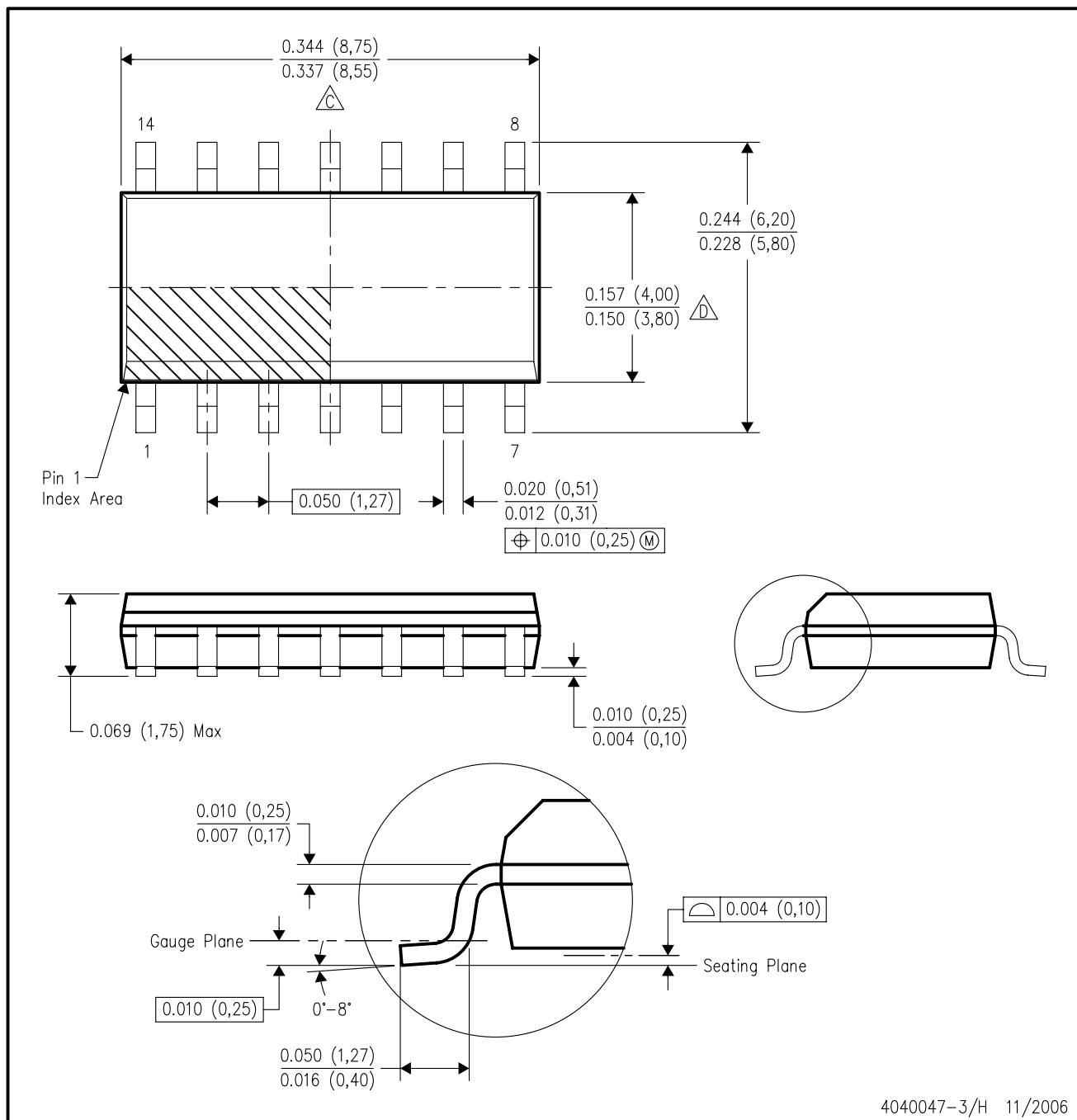
14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AB.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

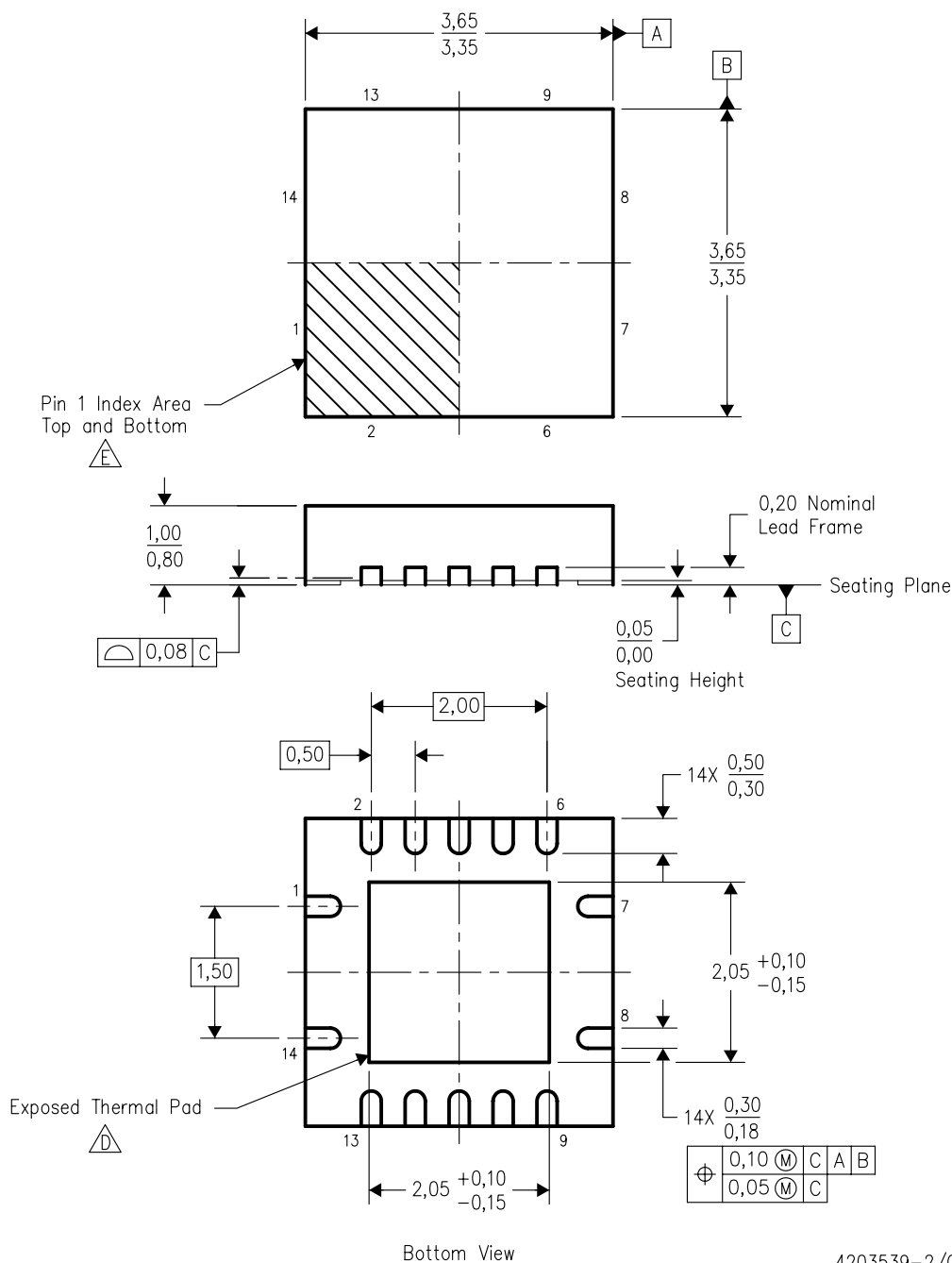
24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

RGY (S-PQFP-N14)

PLASTIC QUAD FLATPACK



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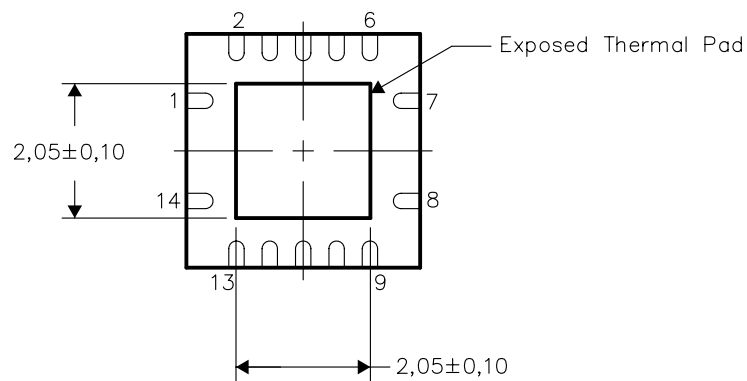
- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - F. Package complies to JEDEC MO-241 variation BA.

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, Quad Flatpack No-Lead Logic Packages, Texas Instruments Literature No. SCBA017. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

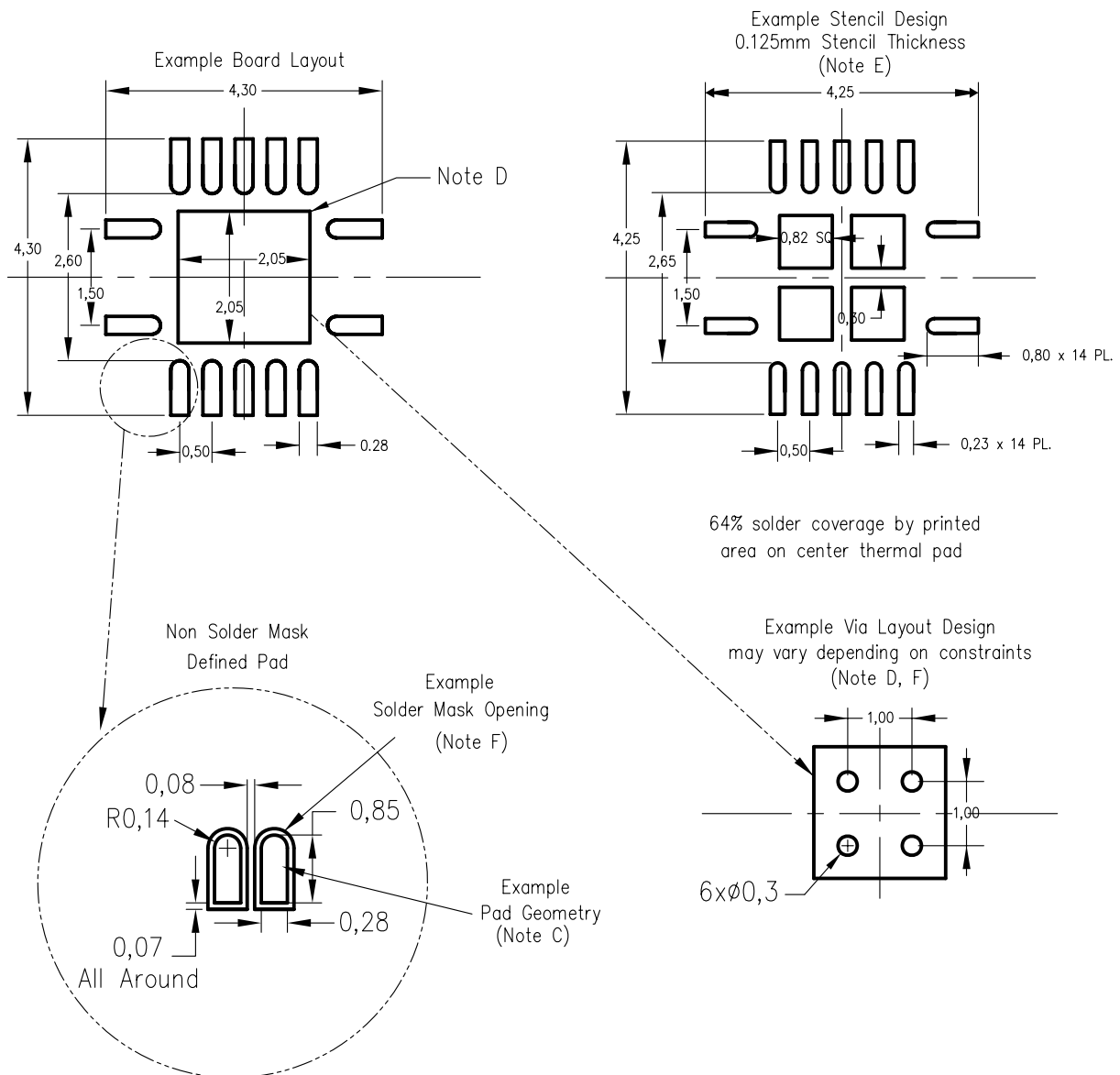


Bottom View

NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

RGY (R-PQFP-N14)



4208122-2/C 09/06

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SCBA017, SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

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